

Page 2 BLOCK DIAGRAM

Page 3 MICROCONTROLLER

Page 4 10/100 ETHERNET INTERFACE FOR INTERNAL MAC+PHY, USB

Page 5 CAN+RS485 EXTERNAL INTERFACE, CAN PHY, RS485 PHY

Page 6 MII / RMII INTERFACE, EXTERNAL DC INPUT

Page 7 POWER SUPPLY 3.3V

Page 8 SPARE AND DEBUG

Page 9 MOUNTING HOLES, FIDUCIALS MARKING

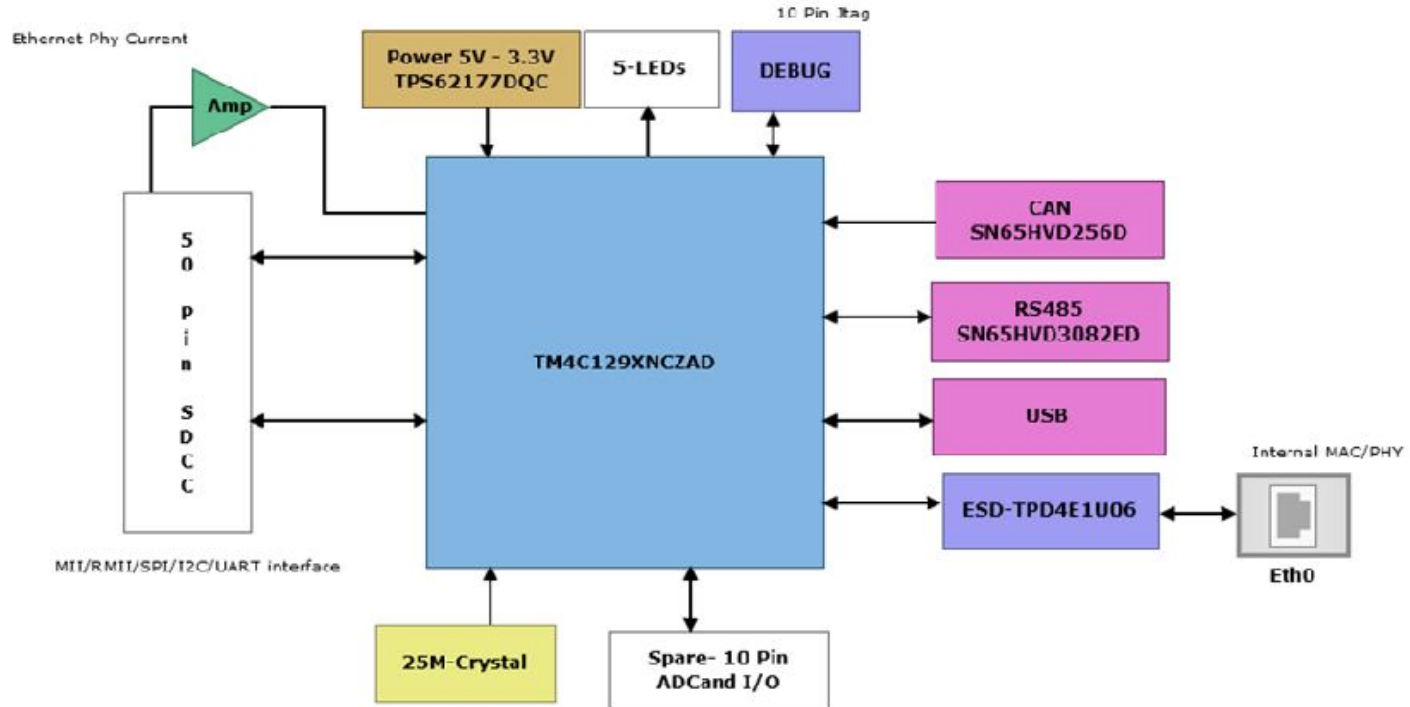
Revision History	
Revision	Notes

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Number: TIDA-00203	Rev: E1	Designed for: Public Release	Mod. Date: 12/16/2014
SVN Rev.: Not in version control		Project Title: CAN-to-Ethernet Converter	
Drawn By:		Sheet Title: Index Page	
Engineer: Sanjay	Assembly Variant: 001	File: Pst1_Index Page_SchDoc	Sheet: 1 of 9
Contact: http://www.ti.com/support		Size: B	

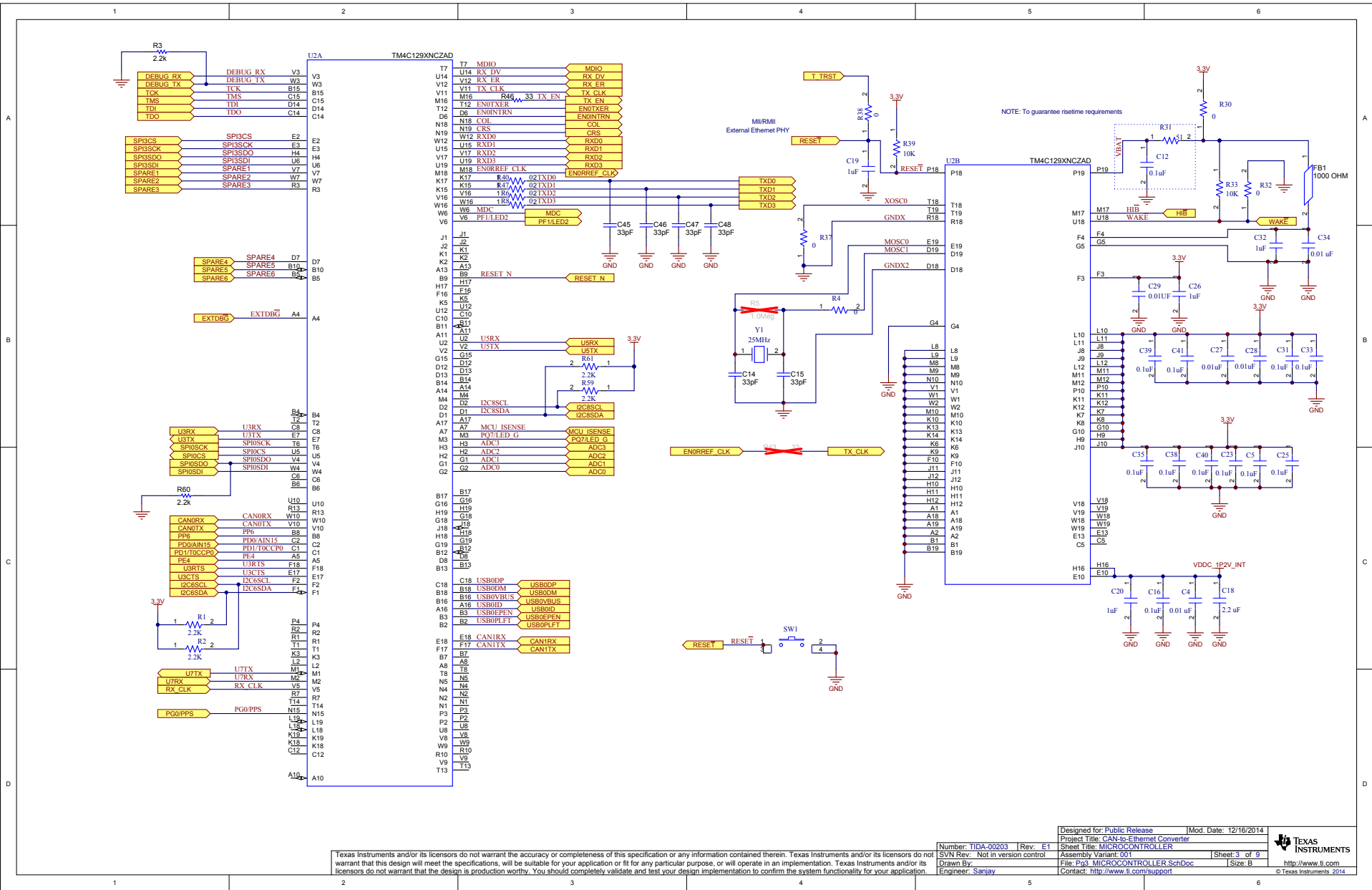


Tiva MCU based Gateway



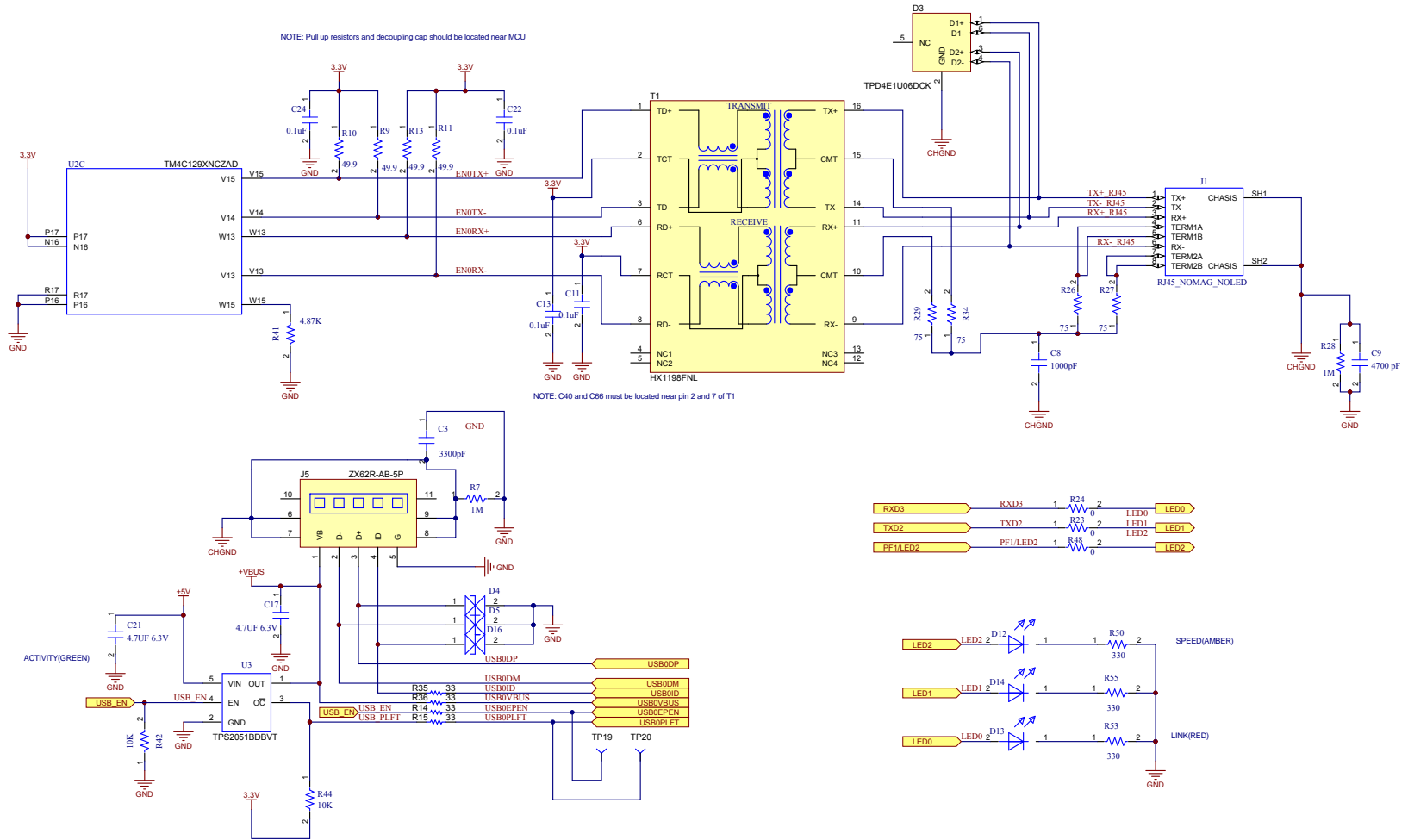
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SVN Rev.: Not in version control		Project Title: CAN-to-Ethernet Converter	
Drawn By:		Sheet Title: BLOCK DIAGRAM	
Engineer: Sanjay		Assembly Variant: 001	Sheet: 2 of 9
		File Path: Block Diagram.SchDoc	Size: B
		Contact: http://www.ti.com/support	

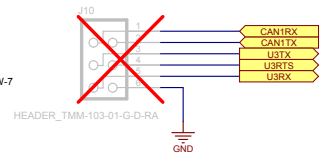
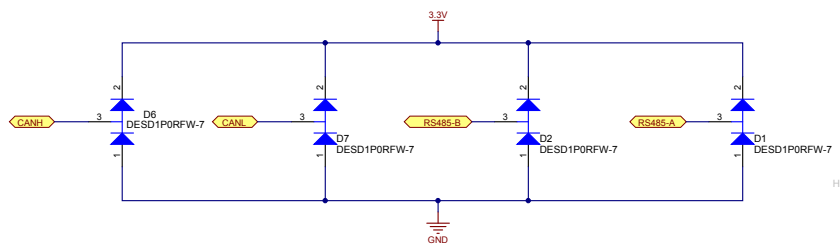
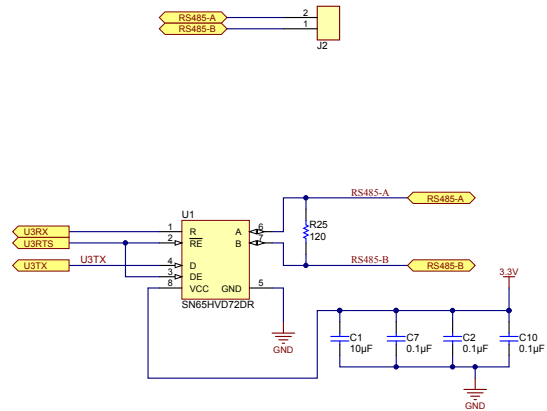
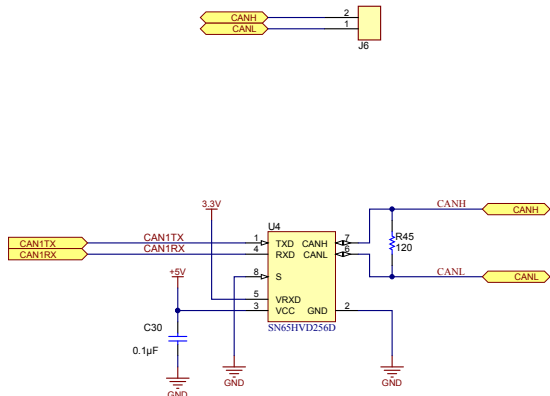


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Number: TIDA-02023	Rev: E1	Designed for: Public Release	Mod. Date: 12/16/2014
SVN Rev.: Not in version control		Project Title: CAN-to-Ethernet Converter	
Assembly Variant: 001		Sheet Title: MICROCONTROLLER	
Drawn By:		File: Pcb_MICROCONTROLLER_SchDoc	
Engineer: Sanjay		Contact: http://www.ti.com/support	
		Sheet: 3 of 9	
		Size: B	
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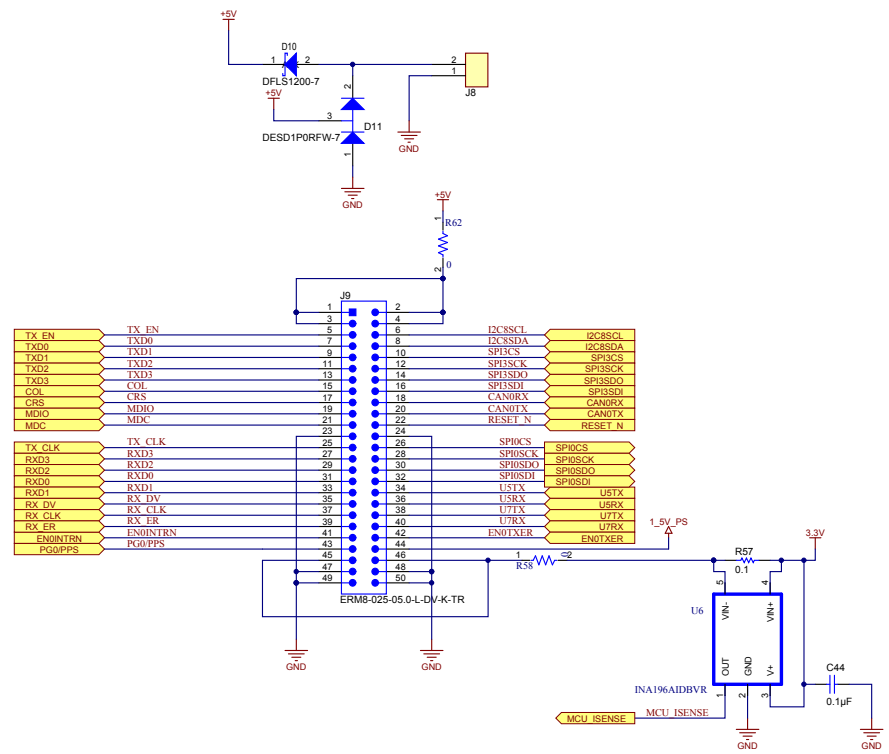
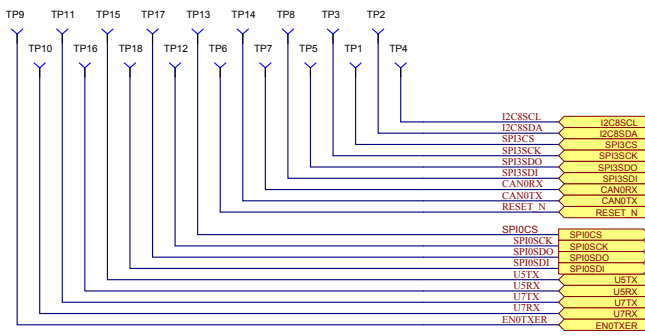


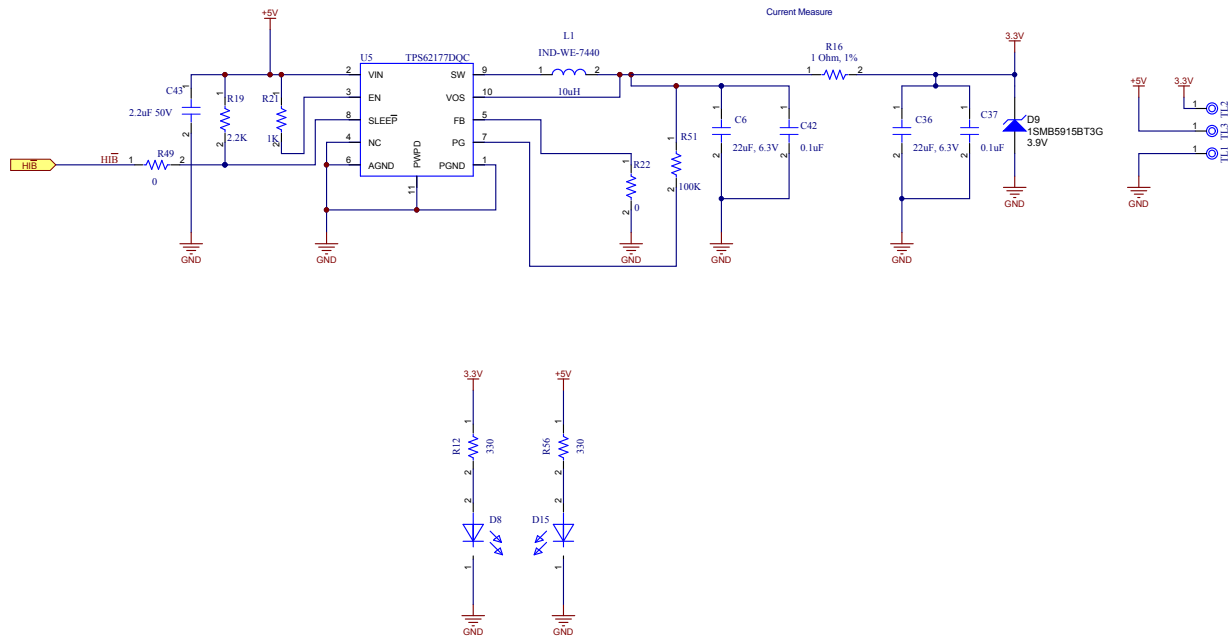
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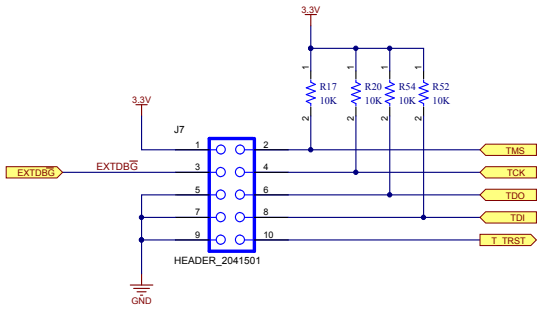
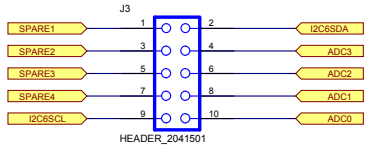
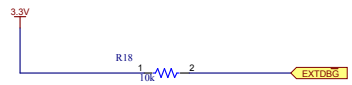




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Designed for: Public Release		Mod. Date: 12/16/2014	
Project Title: POWER SUPPLY			
Number: TIDA-00203		Rev: E1	
SVN Rev.: Not in version control		Assembly Variant: 30T	
Drawn By: Engineer: Sanjay		Sheet: 7 of 9	
File: Pwr_SUPPLY_SchDoc		Size: B	
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Number: TIDA-00203	Rev: E1	Designed for: Public Release	Mod. Date: 12/16/2014
SVN Rev.: Not in version control		Project Title: CAN-to-Ethernet Converter	
Drawn By: Engineer: Sanjay		Sheet Title: SPARE AND DEBUG	
		Assembly Variant: 001	Sheet: 6 of 9
		File: Pcb_SPARE_AND_DEBUG_SchDoc	Size: B
		Contact: http://www.ti.com/support	

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H1 NY PMS 440 0025 PH H2 NY PMS 440 0025 PH H5 NY PMS 440 0025 PH H6 NY PMS 440 0025 PH H3 NY PMS 440 0025 PH H4 NY PMS 440 0025 PH

FID5 FID6 FID4 FID3 FID2 FID1

PCB Number: TIDA-00203
PCB Rev: E1

PCB
LOGO
Texas Instruments

Label Table	
Variant	Label Text
001	ChangeMe!
002	ChangeMe!

LBL1
PCB Label
Size: 0.65" x 0.20"


Z24
Label Assembly Note
This Assembly Note is for PCB labels only

Z23
Assembly Note
These assemblies are ESD sensitive, ESD precautions shall be observed.

Z21
Assembly Note
These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

Z22
Assembly Note
These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.

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SVN Rev.: Not in version control	Assembly Variant: 001	Project Title: CAN-to-Ethernet Converter	Sheet 2 of 9
Drawn By:	File: Pcb_Hardware_ANSI-B_SchDoc	Sheet Title: MOUNTING HOLES, FIDUCIALS MARKING	Size: B
Engineer: Sanjay	Contact: http://www.ti.com/support	 http://www.ti.com © Texas Instruments 2014	

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